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2018 PRODUCT SELECTION GUIDE

- Specialty DRAM
- Mobile DRAM
- Code Storage Flash Memory

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ABOUT WINBOND

Winbond Electronics Corporation is a leading global supplier of specialty memory solutions.

The Company provides customer-driven memory solutions backed by the expert capabilities of product design, R&D, manufacturing, and sales services.

Winbond's product portfolio, consisting of Specialty DRAM, Mobile DRAM, Code Storage Flash, is widely used by tier-1 customers in the consumer, communication, computer peripheral, automotive and industrial markets. Based on a 300 mm wafer fab, Winbond keeps pace with the latest technologies to provide high-quality memory IC products.

Winbond headquarters in Central Taiwan Science Park, Taiwan, and has subsidiaries in America, Japan, China, Israel and Hong Kong.



SPECIALTY DRAM

• The products listed above may not be available for all regions.
Please contact your local Winbond Sales Representative.

■ Density

- 16~256Mb SDR
- 32~256Mb DDR
- 128Mb~2Gb DDR2
- 512Mb~4Gb DDR3

■ Speed

- SDR-200
- DDR-500
- DDR2-1066
- DDR3-1866
- DDR3-2133

■ Package

- JEDEC standard
- Special BGA package support on SDR and DDR for portable devices.

■ Interface

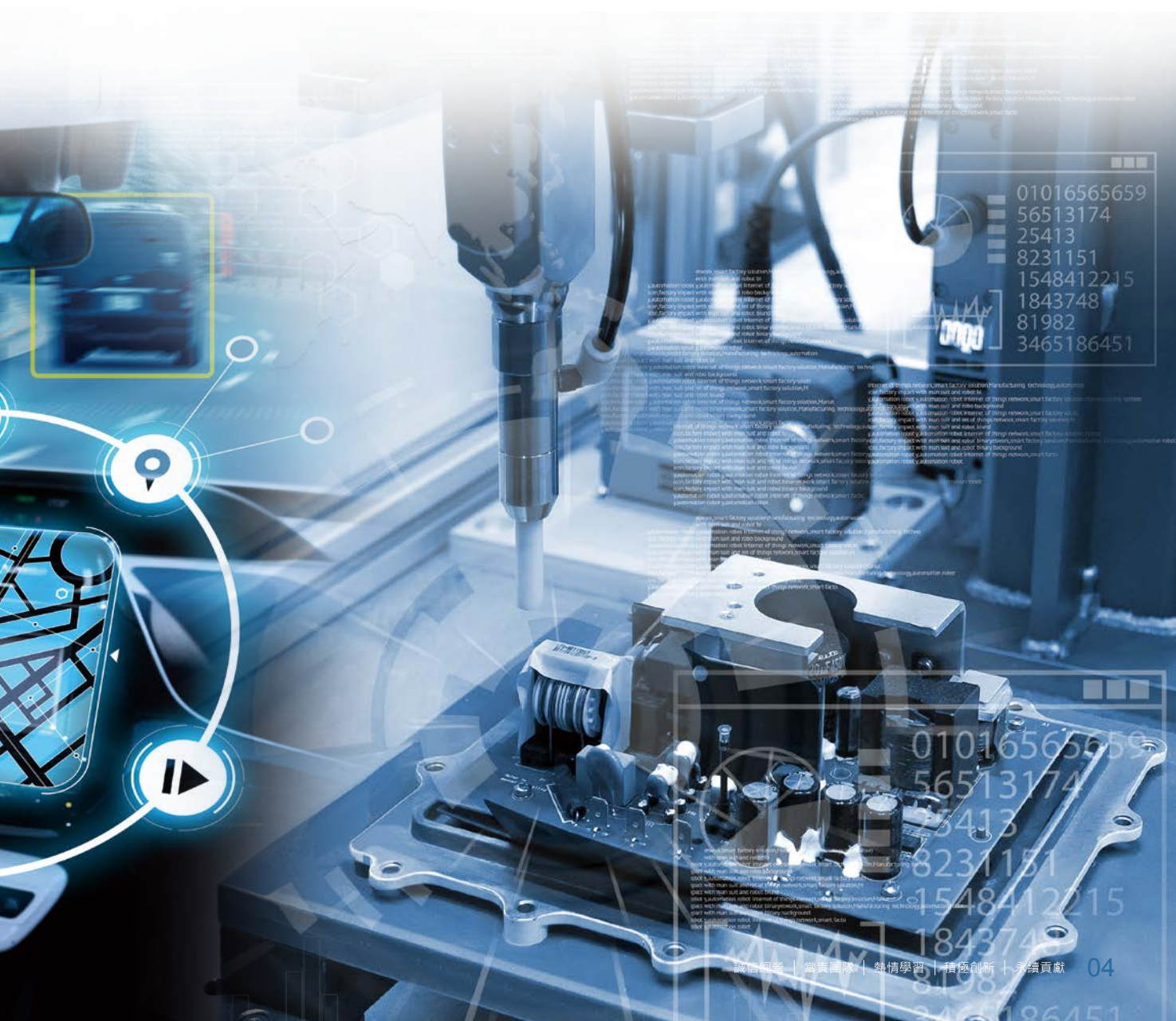
- x16/x32 SDR/DDR
- x8/x16 DDR2/DDR3



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- Support customized KGD solutions including RDL & wild range power domains
- I-temp/Automotive support on SDR/DDR/DDR2/DDR3 products



SDRAM

■ 16Mb (2MB)

Part No.	Organization	Voltage	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W9816G6JH	1Mb x16	3.3V±0.3V	-5/-5I	TSOPII 50	P	P
		2.7V~3.6V	-6/-6I/-6A/-6K/-6W -7/-7I			
W9816G6JB	1Mb x16	3.3V±0.3V	-5/-5I	FBGA 60	P	P
		2.7V~3.6V	-6/-6I/-6A/-6K/-6W -7/-7I			

■ 64Mb (8MB)

Part No.	Organization	Voltage	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W9864G6JB	4Mb x16	3.3V±0.3V	-6/-6I/-6A/-6K/-6W	FBGA 60	P	P
		2.7V~3.6V	-7/-7I			
W9864G6JT	4Mb x16	3.3V±0.3V	-6/-6I/-6A/-6K/-6W	FBGA 54	P	P
W9864G6KH	4Mb x16	3.3V±0.3V	-5/-5I	TSOP II 54	P	P
		2.7V~3.6V	-6/-6I/-6A/-6K/-6W -7/-7I			
W9864G2JB	2Mb x32	3.3V±0.3V	-5/-5I	FBGA 90	P	P
		2.7V~3.6V	-6/-6I/-6A/-6K/-6W -7/-7I			
W9864G2JH	2Mb x32	3.3V±0.3V	-5/-5I	TSOPII 86	P	P
		2.7V~3.6V	-6/-6I/-6A/-6K/-6W -7/-7I			



■ 128Mb (16MB)

Part No.	Organization	Voltage	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W9812G6JB	8Mb x16	3.3V±0.3V	-6/-6I/-6A/-6K/-6W	FBGA 54	P	P
W9812G6KH	8Mb x16	3.3V±0.3V	-5/-5I	TSOP II 54	P	P
			-6/-6I/-6A/-6K/-6W			
W9812G2KB	4Mb x32	3.3V±0.3V	-6/-6I/-6A/-6K/-6W	FBGA 90	P	P

■ 256Mb (32MB)

Part No.	Organization	Voltage	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W9825G2JB	8Mb x32	3.3V±0.3V	-6/-6I/-6A/-6K/-6W	FBGA 90	P	P
W9825G6JB	16Mb x16	3.3V±0.3V	-6/-6I/-6A/-6K/-6W	FBGA 54	P	P
W9825G6KH	16Mb x16	3.3V±0.3V	-5/-5I	TSOP II 54	P	P
			-6/-6I/-6A/-6K/-6W			

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Status²: All Winbond products are "Green", Halogen-Free and RoHS compliant packaging. Refer to the datasheet for details and specifications.

Automotive³: If you need any information of automotive part, please send your request to DRAM-Automotive@winbond.com

Grade code⁴: I=Industrial, A=Automotive grade3, K= Automotive Grade2, W= Automotive Tc -40°C ~ 115°C.

Contact us: SDRAM@winbond.com



DDR SDRAM

■ 64Mb (8MB)

Part No.	Organization	Voltage	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W9464G6KH	4Mbx16	2.5V±0.2V	-5/-5I/-5A/-5K/-5W	TSOP16 66	P	P

■ 128Mb (16MB)

Part No.	Organization	Voltage	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W9412G6JB	8Mbx16	2.5V±0.2V	-5/-5I	TFBGA 60	P	P
W9412G6KH	8Mbx16	2.5V±0.2V	-5/-5I/5A/5K/-5W	TSOP16 66	P	P

■ 256Mb (32MB)

Part No.	Organization	Voltage	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W9425G6JB	16Mbx16	2.5V ±0.2V	-5/-5I	TFBGA 60	P	P
W9425G6KH	16Mbx16	2.5V ±0.2V	-5/-5I/5A/5K/-5W	TSOP16 66	P	P

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DDR2 SDRAM

■ 128Mb (16MB)

Part No.	Organization	Voltage	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W9712G6KB	8Mbx16	1.8V±0.1V	-25/25I/25J/25A/25K/25W	FBGA 84	P	P

■ 256Mb (32MB)

Part No.	Organization	Voltage	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W9725G6KB	16Mbx16	1.8V±0.1V	-18/18I/18J	FBGA 84	P	P
			-25/25I/25J//25A/ 25K/25W			
W9725G8KB	32Mbx8	1.8V±0.1V	-18/18I/18J	FBGA 60	P	P
			-25/25I/25J//25A/ 25K/25W			

■ 512Mb (64MB)

Part No.	Organization	Voltage	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W9751G6KB	32Mbx16	1.8V±0.1V	-15	FBGA 84	P	P
			-18/18I/18J			
			-25/25I/25J/25A/25K/25W			
W9751G8KS	64Mbx8	1.8V±0.1V	-18/18I/18J	FBGA 60	P	P
			-25/25I/25J/25A/25K/25W			

■ 1Gb (128MB)

Part No.	Organization	Voltage	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W971GG6SB	64Mbx16	1.8V±0.1V	-18/18I	FBGA 84	P	P
			-25/25I/25J/25A/25K/25W			
W971GG8SB	128Mbx8	1.8V±0.1V	-18/18I	FBGA 60	P	P
			-25/25I/25J/25A/25K/25W			

■ 2Gb (256MB)

Part No.	Organization	Voltage	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W972GG6KB	128Mbx16	1.8V±0.1V	-18/18I	FBGA 84	P	P
			-25/25I/25J/25A/25K/25W			
W972GG8KS	256Mbx8	1.8V±0.1V	-18/18I	FBGA 60	P	P
			-25/25I/25J/25A/25K/25W			

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Contact us: SDRAM@winbond.com



DDR3 SDRAM

■ 512Mb (64MB)

Part No.	Organization	Voltage	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W6351G6KB	64Mbx16	1.5V±0.075V	-11/111	FBGA 96	P	-
			-12/12I/12J			
			-15/15I/15J			

■ 1Gb (128MB)

Part No.	Organization	Voltage	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W631GG6MB	64Mbx16	1.5V±0.075V	-09/09I/09J/09A/09K/09W	FBGA 96	P	P
			-11/11I/11J/11A/11K/11W			
			-12/12I/12J/12A/12K/12W			
			-15/15I/15J/15A/15K/15W			
W631GG8MB	128Mbx8	1.5V±0.075V	-09/09I/09J/09A/09K/09W	FBGA 78	P	P
			-11/11I/11J/11A/11K/11W			
			-12/12I/12J/12A/12K/12W			
			-15/15I/15J/15A/15K/15W			
W631GU6MB	64Mbx16	1.283V to 1.45V	-09/09I/09J/09A/09K/09W	FBGA 96	P	P
			-11/11I/11J/11A/11K/11W			
			-12/12I/12J/12A/12K/12W			
			-15/15I/15J/15A/15K/15W			
W631GU8MB	128Mbx8	1.283V to 1.45V	-09/09I/09J/09A/09K/09W	FBGA 78	P	P
			-11/11I/11J/11A/11K/11W			
			-12/12I/12J/12A/12K/12W			
			-15/15I/15J/15A/15K/15W			



■ 2Gb (256MB)

Part No.	Organization	Voltage	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W632GG6MB	128Mbx16	1.5V±0.075V	-09/09I/09J/09A/09K/09W	FBGA 96	P	P
			-11/11I/11J/11A/11K/11W			
			-12/12I/12J/12A/12K/12W			
			-15/15I/15J/15A/15K/15W			
W632GG8MB	256Mbx8	1.5V±0.075V	-09/09I/09J/09A/09K/09W	FBGA 78	P	P
			-11/11I/11J/11A/11K/11W			
			-12/12I/12J/12A/12K/12W			
			-15/15I/15J/15A/15K/15W			
W632GU6MB	128Mbx16	1.283V to 1.45V	-09/09I/09J/09A/09K/09W	FBGA 96	P	P
			-11/11I/11J/11A/11K/11W			
			-12/12I/12J/12A/12K/12W			
			-15/15I/15J/15A/15K/15W			
W632GU8MB	256Mbitx8	1.283V to 1.45V	-09/09I/09J/09A/09K/09W	FBGA 78	P	P
			-11/11I/11J/11A/11K/11W			
			-12/12I/12J/12A/12K/12W			
			-15/15I/15J/15A/15K/15W			

■ 4Gb (512MB)

Part No.	Organization	Voltage	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W634GG6MB	256Mbx16	1.5V±0.075V	-09/09I/09J/09A/09K/09W	FBGA 96	P	S
			-11/11I/11J/11A/11K/11W			
			-12/12I/12J/12A/12K/12W			
			-15/15I/15J/15A/15K/15W			
W634GG8MB	512Mbx8	1.5V±0.075V	-09/09I/09J/09A/09K/09W	FBGA 78	P	S
			-11/11I/11J/11A/11K/11W			
			-12/12I/12J/12A/12K/12W			
			-15/15I/15J/15A/15K/15W			
W634GU6MB	256Mbx16	1.283V to 1.45V	-09/09I/09J/09A/09K/09W	FBGA 96	P	S
			-11/11I/11J/11A/11K/11W			
			-12/12I/12J/12A/12K/12W			
			-15/15I/15J/15A/15K/15W			
W634GU8MB	512Mbx8	1.283V to 1.45V	-09/09I/09J/09A/09K/09W	FBGA 78	P	S
			-11/11I/11J/11A/11K/11W			
			-12/12I/12J/12A/12K/12W			
			-15/15I/15J/15A/15K/15W			

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Contact us: SDRAM@winbond.com

KGD

Fully Cover all Consumer Applications:

TV, STB, Networking, Storage, Printer, DSC/DV, GPS, Automotive...etc.
 Providing KGD services to SiP customers with complete DRAM product portfolio such as SDRAM, DDR, DDR2, DDR3.

Wafer Level high speed test:

Up to DDR3 1600Mbps, DDR2 1066Mbps, DDR 500Mbps.
 Winbond provides professional advices to KGD customers, including SiP package bonding & power/thermal, DRAM simulation,...etc.

Excellent KGD Quality Control:

With AEC-Q100, TS16949, ISO9001/14001, OHSAS18001 certificates for automotive customers.
 Owing one 12-inch Fab6 to guarantee stable long-term delivery.

Please Contact DRAM-KGD@winbond.com

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MOBILE DRAM

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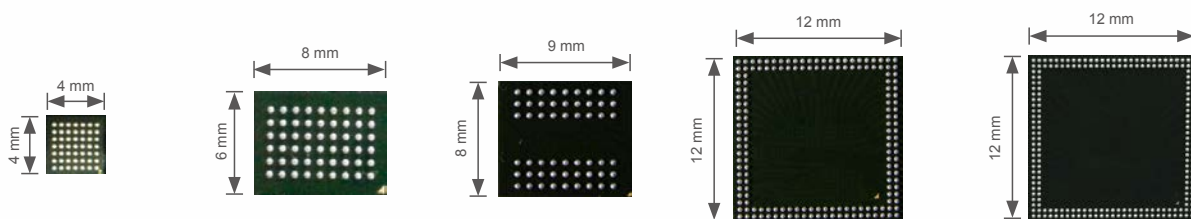
Winbond Electronics Corporation is a leading supplier of semiconductor solutions to the consumer, computer, communications, and electronics product markets. With the latest Buried Word Line technology, Winbond developed the mobile DRAM devices with a low IDD current value, which helps Winbond to extend mobile DRAM memory applications beyond the mobile phone and tablet market to areas of mobile consumer electronics and mobile communication.

Winbond mobile DRAM devices support both x8,x16,x32 and x64 data widths. Major features for the families of products shown in the table below include the following: Sequential or Interleave burst, High Clock rate, Standard Self Refresh, Partial-Array Self Refresh (PASR), Automatic Temperature Compensated Self Refresh Rate (ATCSR), Deep Power-Down (DPD), Programmable output buffer driver strength, and Temperature sensor output (TQ). Please refer to the datasheets for specific features. They are ideal for portable multimedia players, eBook Readers, automotive applications, consumer electronics, gaming devices, and mobile devices.

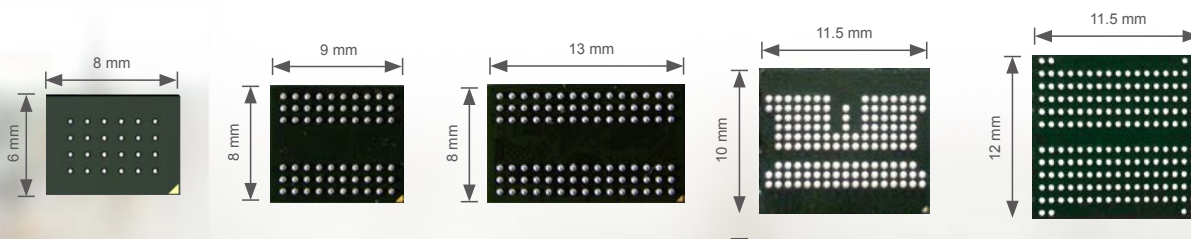


Product	I/O	Ball count	Type	Dimension	Remark
pSRAM	X16	49	BGA	4x4	-
	X8	24	BGA	6x8	-
	X16	54	BGA	6x8	JEDEC standard
LPSDR	X16	54	BGA	8x9	JEDEC standard
	X32	90	BGA	8x13	JEDEC standard
LPDDR	X16	60	BGA	8x9	JEDEC standard
	X32	90	BGA	8x13	JEDEC standard
LPDDR2	X16 / X32	168	PoP	12x12	JEDEC standard
		134	BGA	10x11.5	JEDEC standard
LPDDR3	X16 / X32	178	BGA	11x11.5	JEDEC standard
	X64	216	PoP	12x12	JEDEC standard

- pSRAMx16_49BGA
- pSRAMx16_54BGA
- LPSDRx16_54BGA(G)
- LPDDR2_168WFBGA(Q)
- LPDDR2/3_216WFBGA(R)



- pSRAMx16_24BGA
- LPDDRx16_60BGA(H)
- LPSDR/LPDDRx32_90BGA(J)
- LPDDR2_134VFBGA(V)
- LPDDR3_178VFBGA(V)



Low Power SDR SDRAM

■ 128Mb (16MB)

Part No.	Organization	Voltage	Speed	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W987D6HBGX	8Mb x16	1.8V / 1.8V	166MHz	-6I/-6E	54VFBGA	N	-
W987D2HBJX	4Mb x32				90VFBGA		

■ 256Mb (32MB)

Part No.	Organization	Voltage	Speed	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W988D6FBGX	16Mb x16	1.8V / 1.8V	166MHz	-6I/-6E	54VFBGA	N	-
W988D2FBJX	8Mb x32				90VFBGA		

■ 512Mb (64MB)

Part No.	Organization	Voltage	Speed	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W989D6KBGX	32Mb x16	1.8V / 1.8V	166MHz	-6I/-6E	54VFBGA	N	-
W989D2KBJX	16Mb x32				90VFBGA		
W989D6DBGX	32Mb x16				54VFBGA	P	-
W989D2DBJX	16Mb x32				90VFBGA		

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Automotive³: If you need any information of automotive part, please send your request to DRAM-Automotive@winbond.com

Grade code⁴: I=Industrial, E=Extended

Contact us: LPDRAM@winbond.com



Low Power DDR SDRAM

■ 128Mb (16MB)

Part No.	Organization	Voltage	Speed	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W947D6HBH	8Mb x16	1.8V / 1.8V	166MHz	-5I/-5E/-6I/-6E	60VFBGA	N	-
W947D2HBJ	4Mb x32		200MHz		90VFBGA		

■ 256Mb (32MB)

Part No.	Organization	Voltage	Speed	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W948D6FBH	16Mb x16	1.8V / 1.8V	166MHz 200MHz	-5I/-5E/-5A/-5K/-5W	60VFBGA	N	N
W948D2FBJ	8Mb x32			-6I/-6E/-6A/-6K/-6W	90VFBGA		
W948D6KBH	16Mb x16			-5I/-5E/-6I/-6E	60VFBGA	P	P
W948V6KBH(DSR ⁵)							

■ 512Mb (64MB)

Part No.	Organization	Voltage	Speed	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W949D6KBH	32Mb x16	1.8V / 1.8V	166MHz 200MHz	-5I/-5E/-6I/-6E	60VFBGA	N	-
W949D2KBJ	16Mb x32				90VFBGA		
W949D6DBH	32Mb x16			-5I/-5E/-5A/-5K/-5W	60VFBGA	P	P
W949D2DBJ	16Mb x32			-6I/-6E/-6A/-6K/-6W	90VFBGA		

■ 1Gb (128MB)

Part No.	Organization	Voltage	Speed	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W94AD6KBH	64Mb x16	1.8V / 1.8V	166MHz	-5I/-5E/-5A/-5K/-5W	60VFBGA	P	P
W94AD2KBJ	32Mb x32		200MHz	-6I/-6E/-6A/-6K/-6W	90VFBGA		

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DSR⁵: With DSR(Deep Self-Refresh) mode feature which can save 70% power compared with normal one

Contact us: LPDRAM@winbond.com



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Low Power DDR2 SDRAM

■ 256Mb (32MB)

Part No.	Organization	Voltage	Speed	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W978H6KBVX	16Mb x16	1.8V / 1.2V	400MHz 533MHz	-1I/-1E/-2I/-2E	134VFBGA	P	-
W978H2KBVX	8Mb x32				134VFBGA		
W978H6KBVA	16Mb x16			-1A/-1K/-1W -2A/-2K/-2W	134VFBGA	-	P
W978H2KBVA	8Mb x32				134VFBGA		

■ 512Mb (64MB)

Part No.	Organization	Voltage	Speed	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³		
W979H6KBQX	32Mb x16	1.8V / 1.2V	400MHz 533MHz	-1I/-1E/-2I/-2E	168WFBGA(PoP)	P	-		
W979H2KBQX	16Mb x32				134VFBGA				
W979H6KBVX	32Mb x16			1.8V / 1.2V	400MHz 533MHz	-1A/-1K/-1W -2A/-2K/-2W	168WFBGA(PoP)	-	P
W979H2KBVX	16Mb x32						134VFBGA		
W979H6KBQA	32Mb x16	-1A/-1K/-1W -2A/-2K/-2W	168WFBGA(PoP)			-	P		
W979H2KBQA	16Mb x32		134VFBGA						
W979H6KBVA	32Mb x16								
W979H2KBVA	16Mb x32								

■ 1Gb (128MB)

Part No.	Organization	Voltage	Speed	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³	
W97AH6KBQX	64Mb x16	1.8V / 1.2V	400MHz 533MHz	-1I/-1E/-2I/-2E	168WFPGA(PoP)	P	-	
W97AH2KBQX	32Mb x32				134 VFBGA			
W97AH6KBVX	64Mb x16			-1A/-1K/-1W -2A/-2K/-2W	168WFPGA(PoP)	-	P	
W97AH2KBVX	32Mb x32				134 VFBGA			
W97AH6KBQA	64Mb x16				134 VFBGA			
W97AH2KBQA	32Mb x32				134 VFBGA			
W97AH6KBVA	64Mb x16							
W97AH2KBVA	32Mb x32							

■ 2Gb (256MB)

Part No.	Organization	Voltage	Speed	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W97BH6LBVX	128Mb x16	1.8V / 1.2V	400MHz 533MHz	-2I/-2E	134 VFBGA	P	-
W97BH2LBVX	64Mb x32			-1I/-1E/-2I/-2E			
W97BH6MBVA	128Mb x32			2I/1I	134 VFBGA	S(Q2/'18)	
W97BH2MBVA	64Mb x32			2I/1I	168WFPGA(PoP)	S(Q2/'18)	
W97BH6MBQA	128Mb x32						
W97BH2MBQA	64Mb x32						

Status¹: P= Mass Production, S (Time)= Samples (Ready Time), UD (Time)= Under Development (Ready Time), N= Not recommended for new designs.

Status²: All Winbond products are "Green", Halogen-Free and RoHS compliant packaging. Refer to the datasheet for details and specifications.

Automotive³: If you need any information of automotive part, please send your request to DRAM-Automotive@winbond.com

Grade code⁴: I=Industrial, E=Extended, A=Automotive grade3, K= Automotive Grade2, W=Automotive Tc -40~115°C

Contact us: LPDRAM@winbond.com

Low Power DDR3 SDRAM

■ 1Gb (128MB)

Part No.	Organization	Voltage	Speed	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W63AH6NBVA	64Mb x16	1.8V / 1.2V	800MHz	-BI/-BE/-CI/-CE	178 VFBGA	S(Q4/" 18)	-
W63AH2NBVA	32Mb x32		933MHz				

■ 2Gb (256MB)

Part No.	Organization	Voltage	Speed	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W63BH6MBV	128Mb x16	1.8V / 1.2V	800MHz	-BI/-BE/-CI/-CE/ -DI/-DE	178 VFBGA	S(Q2/" 18)	-
W63BH2MBV	64Mb x32		933MHz				

■ 4Gb (512MB)

Part No.	Organization	Voltage	Speed	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W63CH6MBV	256Mb x16	1.8V / 1.2V	800MHz	-BI/-BE/-CI/-CE	178 VFBGA	S(Q1/" 18)	-
W63CH2MBV	128Mb x 32		933MHz				

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Automotive³: If you need any information of automotive part, please send your request to DRAM-Automotive@winbond.com

Grade code⁴: I=Industrial, E=Extended

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Low Power DDR4 SDRAM

1Gb (128MB)

Part No.	Organization	Voltage	Speed	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W66AL6NBVA	64Mb x16	1.8V/1.1V	3200Mbps	-FE	200BGA	S(Q2/'19)	-

2Gb (256MB)

Part No.	Organization	Voltage	Speed	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W66BL6NBVA	128Mb x16	1.8V/1.1V	3200Mbps	-FE	200BGA	S(Q4/'18)	-

Status¹: P= Mass Production, S (Time)= Samples (Ready Time), UD (Time)= Under Development (Ready Time), N= Not recommended for new designs.

Status²: All Winbond products are "Green", Halogen-Free and RoHS compliant packaging. Refer to the datasheet for details and specifications.

Automotive³: If you need any information of automotive part, please send your request to DRAM-Automotive@winbond.com

Grade code⁴: I=Industrial, E=Extended

Contact us: LPDRAM@winbond.com

Pseudo SRAM

32Mb (4MB)

Part No.	Organization	Voltage	Speed	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W966K6HBG	2Mb x16 CRAM	1.8V / 1.8V	133MHz	-6I/-7I/-6E/-7E	54VFBGA	N	-
W956K6HBC	2Mb x16 CRAM-ADM		166MHz				
W955D8MCY	4Mb x8		166MHz	-6I/-6E	24TFBGA	S(Q2/'18)	

64Mb (8MB)

Part No.	Organization	Voltage	Speed	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W966D6HBG	4Mb x16 CRAM	1.8V / 1.8V	133MHz	-6I/-7I/-6E/-7E	54VFBGA	N	-
W956D6HBC	4Mb x16 CRAM-ADM				49VFBGA		
W956D6KBK	4Mb x16 CRAM-ADM		166MHz	-6I/-6E	24TFBGA	P	
W956D8MCY	8Mb x8		166MHz			S(Q4/'18)	

128Mb (16MB)

Part No.	Organization	Voltage	Speed	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W967D6HBG	8Mb x16 CRAM	1.8V / 1.8V	133MHz	-6I/-7I/-6E/-7E	54VFBGA	P	-
W957D6HBC	8Mb x16 CRAM-ADM		166MHz				
W957D8MCY	16Mb x8		166MHz	-6I/-6E	24TFBGA	UD	

256Mb (32MB)

Part No.	Organization	Voltage	Speed	Speed Grade ⁴	Package	Status ^{1,2}	Automotive ³
W968D6DAG	16Mb x16 CRAM	1.8V / 1.8V	133MHz	-6I/-7I/-6E/-7E	54VFBGA	P	-
W958D6DBC	16Mb x16 CRAM-ADM		166MHz				

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Automotive³: If you need any information of automotive part, please send your request to DRAM-Automotive@winbond.com

Grade code⁴: I=Industrial, E=Extended

Contact us: PSRAM@winbond.com

KGD

Fully Cover all Consumer Application:

PND/GPS, Smart Phone, Industry PDA/POS, E-Reader, Portable Game Console, 3.5G/4G Data Card, AP Router, Pico Projector, Automotive, Touch Model, Smart TV, Smart Grid, Monitor System, IP Cam...etc. Providing KGD service to SiP customers with complete mobile DRAM product such as Mobile SDR, Mobile DDR, Mobile DDR2, Mobile DDR3, pSRAM

Provide Diversification of Low Power Consumption Product:

Support DRAM density as:

-LPDDR/LPDDR: 128Mb to 1Gb

-LPDDR2: 256Mb to 2Gb

-LPDDR3: 1Gb to 4Gb

-LPDDR4: 1Gb to 4Gb

-pSRAM: 32Mb to 128Mb

and support stable, lower power consumption for mobile application

Wafer Level high Speed test:

Up to mobile SDR 166MHz, mobile DDR 400MHz, mobile DDR2 533MHz, mobile DDR3 1066MHz, pSRAM 133MHz (166MHz~200MHz) Winbond provides professional advice to KGD customers, including SiP package bonding & power thermal, mobile DRAM simulation...etc

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100% Burn-In and Test, and qualification of AEC-Q100, TS16949, ISO9001/14001, OHSAS18001 for automotive customers

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CODE STORAGE FLASH MEMORY

• The products listed above may not be available for all regions.
Please contact your local Winbond Sales Representative.

Serial NOR Flash

■ SpiFlash® Memories with SPI, Dual-SPI, Quad-SPI and QPI

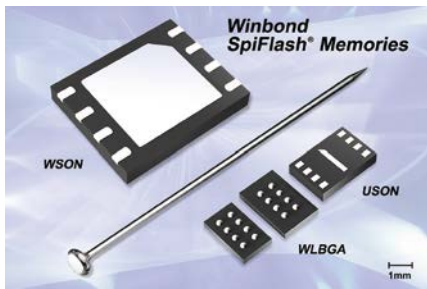
Winbond's W25X and W25Q SpiFlash® Multi-I/O Memories feature the popular Serial Peripheral Interface (SPI), densities from 512M-bit to 512K-bit, small erasable sectors and the industry's highest performance. The W25X family supports Dual-SPI effectively doubling standard SPI clock rates. The W25Q family is a "superset" of the 25X family with Dual-I/O and Quad-I/O SPI for even higher performance. Clock rates up to 133MHz achieve an equivalent of 532MHz (66M-Byte/S transfer rate) when using Quad-SPI. This is multiple times the performance of ordinary Serial Flash (50MHz) and even surpasses asynchronous Parallel Flash memories while using fewer pins and less space. Faster transfer rates mean controllers can execute code (XIP) directly from the SPI interface or further improve boot time when shadowing code to RAM. Additionally, some SpiFlash devices offer Quad Peripheral Interface (QPI) supporting true Quad Commands for improved XIP performance and simpler controller circuitry. Additionally, new ultra-small form factor packages are ideal for space constrained mobile and handheld applications.



Leading the Serial Flash Market in unit sales and revenue, Winbond TS16949 certified AEC-Q100 qualified memories now support automotive applications. The automobile has transformed into the most sophisticated electronic device in the market. Digital displays in automotive dashboards provide more information about the car, and improve safety. Instant-on and real time 2D/3D image rendering is achieved with fast processors and SpiFlash memories. ADAS (Advanced Driver Assist Systems), comfort, entertainment, and navigation is now available in the center console and this is addressed with SpiFlash memories using small packages for space constrained systems and high density for advanced applications.

Please contact Winbond for automotive datasheet and support.

Tiny Serial Flash Packages



Winbond Industrial and Automotive Grade Memory

	Industrial	Industrial Plus	Automotive Grade 3	Automotive Grade 2
Temperature Range	-40°C ~85°C	-40°C ~105°C	-40°C ~85°C	-40°C ~105°C
Part# Example	W25Q80BVSSIG	W25Q80BVSSJG	W25Q80BVSSBG	W25Q80BVSSAG
AEC-Q100 Compliant	No	No	Yes	Yes
Change Control	No	No	Optional	Optional



Serial NOR Flash

■ 512Mb (64MB)

Part No.	Features	Voltage	Speed (MHz)	Package(s)	Status ^{1,2}	Automotive ⁵
W25M512JV	Dual/Quad-SPI, Enhanced ³	2.7V - 3.6V	104	SOIC16 300mil, WSON8 8X6mm, TFBGA24 6X8mm (4x6 Matrix) ⁴ , TFBGA24 6X8mm (5x5 Matrix) ⁴	P	UD
W25M513JV	Dual/Quad-SPI, QPI, DTR, Enhanced ³	2.7V - 3.6V	80/133	SOIC16 300mil, WSON8 8X6mm, TFBGA24 6X8mm (4x6 Matrix) ⁴ , TFBGA24 6X8mm (5x5 Matrix) ⁴	P	UD
W25H512JV	Dual/Quad-SPI, QPI, DTR, Enhanced ³ , On-chip ECC	2.7V - 3.6V	104/133	SOIC16 300mil, WSON8 8X6mm, TFBGA24 6X8mm (4x6 Matrix) ⁴ , TFBGA24 6X8mm (5x5 Matrix) ⁴	UD	UD
W25H512NW	Dual/Quad-SPI, QPI, DTR, Enhanced ³ , On-chip ECC	1.65V - 1.95V	104/133	SOIC16 300mil, WSON8 8X6mm, TFBGA24 6X8mm (4x6 Matrix) ⁴ , TFBGA24 6X8mm (5x5 Matrix) ⁴	UD	UD
W25M512JW	Dual/Quad-SPI, Enhanced ³	1.7V - 1.95V	104	SOIC16 300mil, WSON8 8X6mm, TFBGA24 6X8mm (4x6 Matrix) ⁴ , TFBGA24 6X8mm (5x5 Matrix) ⁴	S	UD

■ 256Mb (32MB)

Part No.	Features	Voltage	Speed (MHz)	Package(s)	Status ^{1,2}	Automotive ⁵
W25Q256JV	Dual/Quad-SPI, Enhanced ³	2.7V - 3.6V	133	SOIC16 300mil, WSON8 8X6mm, TFBGA24 6X8mm (4x6 Matrix) ⁴ , TFBGA24 6X8mm (5x5 Matrix) ⁴	P	UD
W25Q256JV-DTR	Dual/Quad-SPI, QPI, DTR, Enhanced ³	2.7V - 3.6V	133	SOIC16 300 mil, WSON8 8x6mm, TFBGA24 6X8mm (4x6 Matrix), TFBGA24 6X8mm (5x5 Matrix)	P	UD
W25R256JV	Dual/Quad-SPI, RPMC, Enhanced ³	2.7V - 3.6V	133	SOIC16 300mil ⁴ , WSON 8x6mm,	P	-
W25H256JV	Dual/Quad-SPI, QPI, DTR, Enhanced ³ , On-chip ECC	2.7V - 3.6V	80/133	SOIC16 300 mil, WSON8 8x6mm, TFBGA24 6X8mm (5x5 Matrix)	P	UD
W25Q256FV	Dual/Quad-SPI, QPI, Enhanced ³	2.7V - 3.6V	104	SOIC16 300mil, WSON8 8X6mm, TFBGA24 6X8mm (4x6 Matrix) ⁴ , TFBGA24 6X8mm (5x5 Matrix) ⁴	N	P
W25Q256JW	Dual/Quad-SPI, Enhanced ³	1.7V - 1.95V	133	SOIC16 300mil, WSON8 8X6mm, TFBGA24 6X8mm (4x6 Matrix) ⁴ , TFBGA24 6X8mm (5x5 Matrix) ⁴	P	UD
W25Q256JW-DTR	Dual/Quad-SPI, QPI, DTR, Enhanced ³	1.7V - 1.95V	133	SOIC16 300mil, WSON8 8X6mm, TFBGA24 6X8mm (4x6 Matrix) ⁴ , TFBGA24 6X8mm (5x5 Matrix) ⁴	P	UD

■ 128Mb (16MB)

Part No.	Features	Voltage	Speed (MHz)	Package(s)	Status ^{1,2}	Automotive ⁵
W25Q128JV	Dual/Quad-SPI, Enhanced ³	2.7V - 3.6V	133	SOIC8 208mil, SOIC16 300mil, WSON8 6X5mm, WSON8 8X6mm, TFBGA24 6X8mm (4x6 Matrix) ⁴ , TFBGA24 6X8mm (5x5 Matrix) ⁴ , VSOP8 208mil ⁴ , PDIP8 300mil	P	UD
W25Q128JV-DTR	Dual/Quad-SPI, QPI, DTR, Enhanced ³	2.7V - 3.6V	133	SOIC8 208mil, SOIC16 300mil, WSON8 6X5mm, WSON8 8X6mm, TFBGA24 6X8mm (4x6 Matrix) ⁴ , TFBGA24 6X8mm (5x5 Matrix) ⁴ , VSOP8 208mil ⁴ , PDIP8 300mil	P	UD
W25R128JV	Dual/Quad-SPI, RPMC, Enhanced ³	2.7V - 3.6V	133	SOIC8 208mil, SOIC16 300mil ⁴ , WSON8 6X5mm ⁴ , VSOP8 208mil ⁴	P	-
W25Q128FV	Dual/Quad-SPI, QPI, Enhanced ³	2.7V - 3.6V	104	SOIC8 208mil, SOIC16 300mil, WSON8 6X5mm, WSON8 8X6mm, TFBGA24 6X8mm (4x6 Matrix) ⁴ , TFBGA24 6X8mm (5x5 Matrix) ⁴ , VSOP8 208mil ⁴	N	P
W25Q128FW	Dual/Quad-SPI, QPI, Enhanced ³	1.65V - 1.95V	104	SOIC8 208mil, SOIC16 300mil ⁴ , WSON8 6X5mm	P	UD
W25Q128JW	Dual/Quad-SPI, Enhanced ³	1.7V - 1.95V	133	SOIC8 208mil, SOIC16 300mil ⁴ , WSON8 6X5mm	P	UD
W25Q128JW-DTR	Dual/Quad-SPI, QPI, DTR, Enhanced ³	1.7V - 1.95V	133	SOIC8 208mil, SOIC16 300mil ⁴ , WSON8 6X5mm	P	UD

■ 64Mb (8MB)

Part No.	Features	Voltage	Speed (MHz)	Package(s)	Status ^{1,2}	Automotive ⁵
W25Q64JV	Dual/Quad-SPI, Enhanced ³	2.7V - 3.6V	133	SOIC8 208mil, SOIC16 300mil, WSON8 6X5mm, WSON8 8X6mm, TFBGA24 6X8mm (4x6 Matrix), TFBGA24 6X8mm (5x5 Matrix) ⁴ , VSOP8 208mil ⁴	P	UD
W25Q64JV-DTR	Dual/Quad-SPI, QPI, DTR, Enhanced ³	2.7V - 3.6V	133	SOIC8 208mil, VSOP8 208mil, SOIC16 300mil, PDIP8 300mil, WSON8 6x5mm, WSON8 8x6mm	P	UD
W25R64JV	Dual/Quad-SPI, RPMC, Enhanced ³	2.7V - 3.6V	133	SOIC8 208mil, SOIC16 300mil ⁴ , WSON8 6X5mm ⁴ , VSOP8 208mil ⁴	P	-
W25Q64FV	Dual/Quad-SPI, QPI, Enhanced ³	2.7V - 3.6V	104	SOIC8 208mil, SOIC16 300mil, WSON8 6X5mm, WSON8 8X6mm, TFBGA24 6X8mm (4x6 Matrix), TFBGA24 6X8mm (5x5 Matrix) ⁴ , VSOP8 208mil ⁴	N	P
W25Q64FW	Dual/Quad SPI, QPI, Enhanced ³	1.65V - 1.95V	104	SOIC8 208mil, WSON8 6X5mm, VSOP8 208mil ⁴ , SOIC16 300mil ⁴ , WLCSP8	P	P
W25Q64JW	Dual/Quad SPI, Enhanced ³	1.7V - 1.95V	133	SOIC8 208mil, USON8 4X4mm, USON4X3mm, WSON8 6X5mm, WSON8 8X6mm, TFBGA24 6X8mm (5x5 Matrix) ⁴ , TFBGA24 6X8mm (4x6 Matrix) ⁴ , VSOP8 208mil ⁴	UD	UD
W25Q64JW-DTR	Dual/Quad SPI, QPI, DTR, Enhanced ³	1.7V - 1.95V	133	SOIC8 208mil, USON8 4X4mm, USON4X3mm, WSON8 6X5mm, WSON8 8X6mm, TFBGA24 6X8mm (5x5 Matrix) ⁴ , TFBGA24 6X8mm (4x6 Matrix) ⁴ , VSOP8 208mil ⁴	UD	UD

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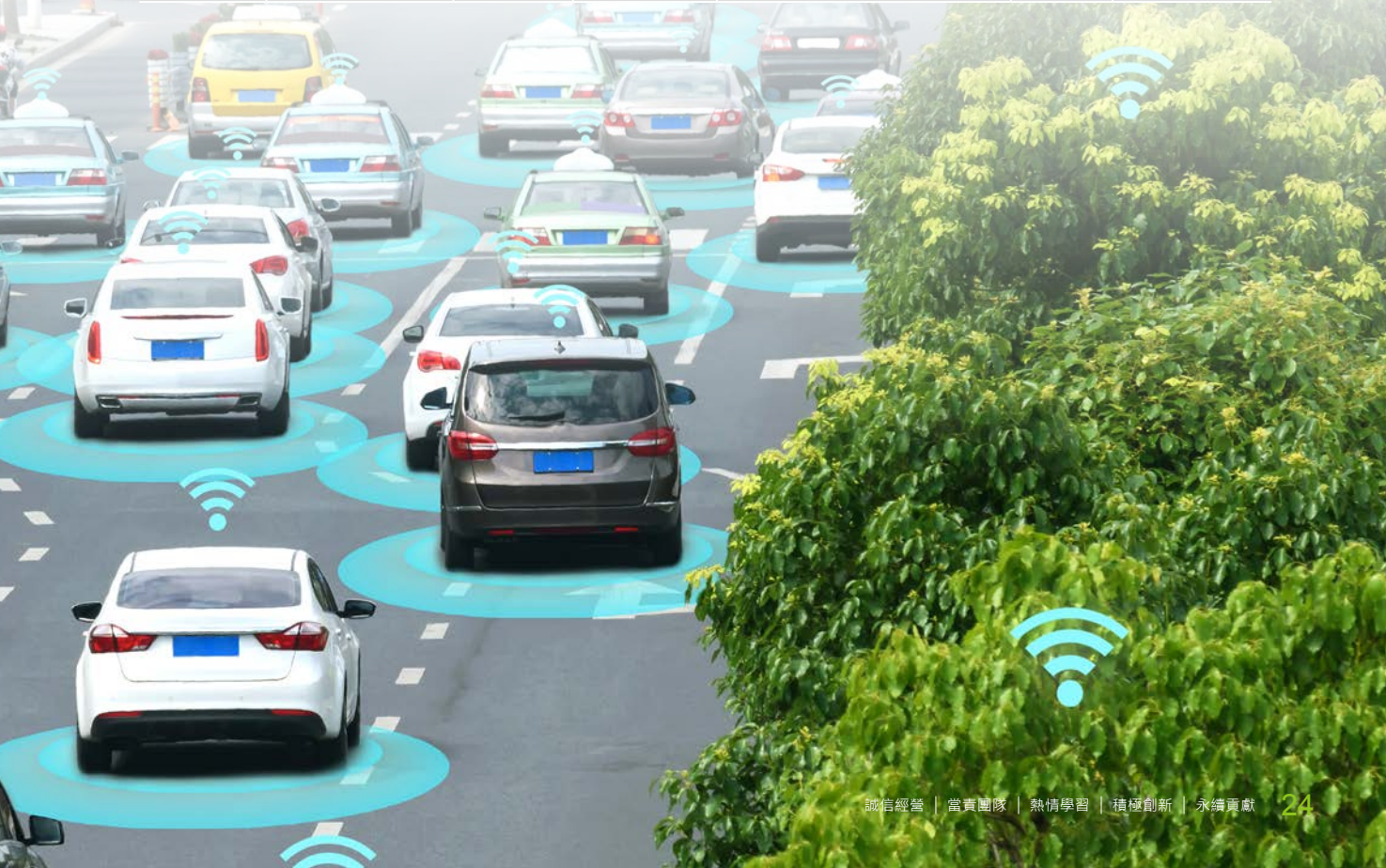
■ 32Mb (4MB)

Part No.	Features	Voltage	Speed (MHz)	Package(s)	Status ^{1,2}	Automotive ⁵
W25Q32JV	Dual/Quad-SPI, Enhanced ³	2.7V - 3.6V	133	SOIC8 208mil, SOIC16 300mil, WSON8 6X5mm, WSON8 8X6mm, TFBGA24 6X8mm (4x6 Matrix) ⁴ , TFBGA24 6X8mm (5x5 Matrix) ⁴ , VSOP8 208mil ⁴ , XSON8 4X4mm ⁴	P	UD
W25Q32JV-DTR	Dual/Quad-SPI, QPI, DTR, Enhanced ³	2.7V - 3.6V	80/133	SOIC8 208mil, VSOP8 208mil, WSON8 6X5mm	P	UD
W25Q32FV	Dual/Quad-SPI, QPI, Enhanced ³	2.7V - 3.6V	104	SOIC8 208mil, SOIC16 300mil, WSON8 6X5mm, WSON8 8X6mm, TFBGA24 6X8mm (4x6 Matrix) ⁴ , TFBGA24 6X8mm (5x5 Matrix) ⁴ , VSOP8 208mil ⁴	N	P
W25Q32JW	Dual/Quad-SPI, Enhanced ³	1.7V - 1.95V	133	SOIC8 208mil, WSON8 6X5mm, VSOP8 208mil ⁴ , WSON8 8X6mm ⁴ , USON8 4X4mm, USON8 4X3mm, WLCSP8 ⁴	P	UD
W25Q32JW-DTR	Dual/Quad-SPI, QPI, DTR, Enhanced ³	1.7V - 1.95V	133	SOIC8 208mil, WSON8 6X5mm, VSOP8 208mil ⁴ , WSON8 8X6mm ⁴ , USON8 4X4mm, USON8 4X3mm, WLCSP8 ⁴	P	UD
W25Q32FW	Dual/Quad SPI, QPI, Enhanced ³	1.65V - 1.95V	104	SOIC8 208mil, WSON8 6X5mm, SOIC16 300mil ⁴ , VSOP8 208mil ⁴ , WSON8 8X6mm ⁴ , XSON8 4X4mm, WLCSP8 ⁴	P	P



■ 16Mb (2MB)

Part No.	Features	Voltage	Speed (MHz)	Package(s)	Status ^{1,2}	Automotive ⁵
W25Q16JV	Dual/Quad-SPI, Enhanced ³	2.7V - 3.6V	80/104	SOIC8 150mil, SOIC8 208mil, WSON8 6X5mm, TFBGA24 6X8mm (4x6 Matrix) ⁴ , TFBGA24 6X8mm (5x5 Matrix) ⁴ , VSOP8 150mil ⁴ , VSOP8 208mil ⁴ , USON8 4X3mm	P	S
W25Q16JV-DTR	Dual/Quad-SPI, QPI,DTR, Enhanced ³	2.7V - 3.6V	80/104	SOIC8 208mil, VSOP8 208mil, WSON8 6x5mm	P	S
W25Q16JL	Dual/Quad SPI, Enhanced ³	2.7V - 3.6V	50/80	SOIC8 150mil, SOIC8 208mil, WSON8 6X5mm, VSOP8 150mil ⁴	P	-
W25Q16DV	Dual/Quad-SPI, Enhanced ³	2.3V - 3.6V	80/104	SOIC8 150mil, SOIC8 208mil, WSON8 6X5mm, SOP16 300mil, TFBGA24 6X8mm (4x6 Matrix) ⁴ , TFBGA24 6X8mm (5x5 Matrix) ⁴ , USON8 4X3mm, USON8 4X4mm, WLCSP8	-	P
W25Q16FW	Dual/Quad SPI, QPI, Enhanced ³	1.65V - 1.95V	104	SOIC8 208mil, WSON8 6X5mm, VSOP8 208mil ⁴ , USON8 2X3mm, USON8 4X3mm, USON8 4X4mm, WLCSP8	P	P
W25Q16DW	Dual/Quad SPI, QPI, Enhanced ³	1.65 - 1.95V and 1.7V - 1.95V	80/104	SOIC8 150mil, SOIC8 208mil, SOIC16 300mil ⁴ , WSON8 6X5mm, USON8 4X3mm, WLCSP8	-	P
W25Q16JW	Dual/Quad SPI, Enhanced ³	1.7V - 1.95V	133	SOIC8 208mil, WSON8 6X5mm, VSOP8 208mil ⁴ , USON8 2X3mm, USON8 4X3mm, USON8 4X4mm, WLCSP8	UD	UD
W25Q16JW-DTR	Dual/Quad SPI, QPI, DTR Enhanced ³	1.7V - 1.95V	133	SOIC8 208mil, WSON8 6X5mm, VSOP8 208mil ⁴ , USON8 2X3mm, USON8 4X3mm, USON8 4X4mm, WLCSP8	UD	UD



Serial NOR Flash
SLC NAND Flash

1.2V Serial NOR Flash
NAND Based MCP

Serial NAND Flash
SpiStack Flash
Authentication Flash

■ 8Mb (1MB)

Part No.	Features	Voltage	Speed (MHz)	Package(s)	Status ^{1,2}	Automotive ⁵
W25Q80DV	Dual/Quad-SPI, Enhanced ³	2.7V - 3.6V	104	SOIC8 150mil, SOIC8 208mil, WSON8 6X5mm, VSOP8 150mil, USON8 2X3mm, WLCSP8 ⁴	P	P
W25Q80DL	Dual/Quad-SPI, Enhanced ³	2.3V - 3.6V	80	SOIC8 150mil, VSOP8 150mil, WSON8 6X5mm, USON8 2X3mm, WLCSP8 ⁴	P	-
W25Q80EW	Dual/Quad-SPI, Fast Write, Enhanced ³	1.65V - 1.95V	104	SOIC8 150mil, SOIC8 208mil, WSON8 6X5mm, VSOP8 150mil, USON8 2X3mm, WLCSP8 ⁴	P	P

■ 4Mb (512KB)

Part No.	Features	Voltage	Speed (MHz)	Package(s)	Status ^{1,2}	Automotive ⁵
W25X40CL	Fast Write, Dual SPI	2.3 – 2.7V and 2.7 – 3.6V	80/104	SOIC8 150mil, VSOP8 150mil, USON 2X3mm, WSON8 6X5mm, SOIC8 208mil	P	-
W25Q40CL	Dual/Quad SPI, Fast Write, Enhanced ³	2.3 – 2.7V and 2.7 – 3.6V	80/104	SOIC8 150mil, SOIC8 208mil, USON8 2X3mm ⁴	P	-
W25Q40CV	Dual/Quad SPI, Fast Write, Enhanced ³	2.7 – 3.6V	80	SOIC8 150mil, SOIC8 208mil, USON8 2X3mm ⁴	-	P
W25Q40EW	Dual/Quad-SPI, Fast Write, Enhanced ³	1.65V - 1.95V	104	SOIC8 150mil, VSOP8 150mil, USON8 2X3mm, USON8 4x3mm ⁴ , WSON8 6X5mm, WLCSP8 ⁴	P	P

■ 2Mb (256KB)

Part No.	Features	Voltage	Speed (MHz)	Package(s)	Status ^{1,2}	Automotive ⁵
W25X20CL	Fast Write, Dual SPI	2.3 – 2.7V and 2.7 – 3.6V	80/104	SOIC8 150mil, VSOP8 150mil ⁴ , USON8 2X3mm, WLCSP8 ⁴	P	-
W25Q20CL	Fast Write, Dual SPI	2.3 - 3.6V and 2.7-3.6V	80/104	SOIC8 150mil, WSON8 6X5mm, VSOP8 150mil, USON8 2X3mm	P	-
W25Q20CV	Fast Write, Dual SPI	2.7 – 3.6V	80	SOIC8 150mil, WSON8 6X5mm, VSOP8 150mil, USON8 2X3mm	-	P
W25Q20EW	Dual/Quad SPI, Fast Write, Enhanced ³	1.65 - 1.95V	104	SOIC8 150mil, USON8 4X3mm, VSOP8 150mil, USON8 2X3mm, WLCSP8 ⁴	P	P

■ 1Mb (128KB)

Part No.	Features	Voltage	Speed (MHz)	Package(s)	Status ^{1,2}	Automotive ⁵
W25X10CL	Fast Write, Dual SPI	2.3 – 3.6V and 2.7 – 3.6V	80/104	SOIC8 150mil, USON8 2X3mm	P	-
W25Q10EW	Dual/Quad SPI, Fast Write	1.65 - 1.95V	104	SOIC8 150mil, VSOP8 150mil ⁴ , USON8 2X3mm,WLCSP8 ⁴	P	P

■ 512Kb (64KB)

Part No.	Features	Voltage	Speed (MHz)	Package(s)	Status ^{1,2}	Automotive ⁵
W25X05CL	Fast Write, Dual SPI	2.3V - 3.6V	104	SOIC8 150mil, TSSOP8 173mil ⁴ , USON 2x3mm	P	-

Status¹: P= Mass Production, S (Time)=Samples (Ready Time), UD (Time)=Under Development (Ready Time), N=Not recommended for new designs

Status²: All Winbond Flash products are "Green", Halogen-Free and RoHS compliant packaging. Refer to the datasheet for details and specifications.

Enhanced³ = SFDP, Security Registers, Program/Erase Suspend/Resume, Word Read Quad I/O, Burst Read with Wrap, Non-Volatile & Volatile Registers, Complement Array Protection

Special Order Packages⁴ = These packages are available, but as special order only and will need a longer lead time prior to production.

Automotive Packages⁵ = Contact Winbond sales for availability of packages on Automotive products.

Contact us: Spiflash@winbond.com

winbond

We Deliver

1.2V Serial NOR Flash

■ SpiFlash® Memories with SPI, Dual-SPI, Quad-SPI

Winbond W25QxxNE 1.2V and W25QxxND extended 1.5V parts are the industry's lowest NOR Flash voltages in 8-pin packages, these newest members of the SpiFlash family provide designers with serial flash memories for mobile, wearable, IoT and other demanding applications that call for low power in small packages. Their low voltages and 52 megabytes per second transfer rate make the new SpiFlash memories optimal for a broad range of consumer and industrial applications.

The new 1.2V and extended 1.5V parts are supplied in 2mm x 3mm USON8, a narrow 150mil SOP8, WSON 6x5mm package and KGD (Known Good Die). The 104MHz speed of the W25QxxNE and W25QxxND series also support operation via standard, dual and quad Serial Peripheral Interface (SPI) and Quad Peripheral Interface (QPI). This provides designers with the flexibility to use low-voltage and low-power serial Flash devices to simplify their power circuitry, with the additional benefit of saving power.

■ Key Features:

Low Power, Wide Temperature Range

- Single 1.14V to 1.3V supply for 1.2V family
- Single 1.14V to 1.6V supply for extended 1.5V family
- 2mA active current
- < 0.5µA Power-down current
- -40°C to +85°C operating range

Flexible Architecture with 4KB sectors

- Uniform sector erase (4K-bytes)
- Uniform block erase (32K and 64K-bytes)
- Programmable one to 256 bytes
- Erase/Program Suspend & Resume

High-Performance Serial Flash

- Single, dual or quad SPI and QPI
- 104MHz clock frequency that can support up to 52Mbytes per second data transfer rates

Space Efficient Packaging

- 8-pin SOIC 150mil
- USON8 2X3mm
- 8-ball WLCSP
- KGD

■ Lower Power Consumption

The reduced power usage in both active and stand-by modes offered by the W25QxxNE series enables system designers to increase battery run-time between charges, or to reduce the size and weight of the battery.

The W25Q80NE, an 8Mbit NOR Flash IC operating from a 1.2V supply, offers a typical power saving in active mode of 33% over the equivalent 1.8V part.

■ 64Mb (8MB)

Part No.	Features	Voltage	Speed (MHz)	Package(s)	Status ^{1,2}	Automotive ⁵
W25Q64NE	Dual/Quad-SPI,QPI, Enhanced ³	1.14V - 1.3V	104	SOIC8 208mil, WSON8 6X5mm	UD	UD

■ 32Mb (4MB)

Part No.	Features	Voltage	Speed (MHz)	Package(s)	Status ^{1,2}	Automotive ⁵
W25Q32NE	Dual/Quad-SPI,QPI, Enhanced ³	1.14V - 1.3V	104	SOIC8 208mil, WSON8 6X5mm	UD	UD

■ 16Mb (2MB)

Part No.	Features	Voltage	Speed (MHz)	Package(s)	Status ^{1,2}	Automotive ⁵
W25Q16NE	Dual/Quad-SPI,QPI, Enhanced ³	1.14V - 1.3V	104	SOIC8 150mil, USON8 4X3mm	UD	UD

■ 8Mb (1MB)

Part No.	Features	Voltage	Speed (MHz)	Package(s)	Status ^{1,2}	Automotive ⁵
W25Q80NE	Dual/Quad-SPI,QPI, Enhanced ³	1.14V - 1.3V	104	SOIC8 150mil, USON8 2X3mm	S	UD
W25Q80ND	Dual/Quad-SPI,QPI, Enhanced ³	1.14V - 1.6V	80	SOIC8 150mil, USON8 2X3mm	S	UD

■ 4Mb (512KB)

Part No.	Features	Voltage	Speed (MHz)	Package(s)	Status ^{1,2}	Automotive ⁵
W25Q40NE	Dual/Quad-SPI,QPI, Enhanced ³	1.14V - 1.3V	104	SOIC8 150mil, USON8 2X3mm	UD	UD

■ 2Mb (256KB)

Part No.	Features	Voltage	Speed (MHz)	Package(s)	Status ^{1,2}	Automotive ⁵
W25Q20NE	Dual/Quad-SPI,QPI, Enhanced ³	1.14V - 1.3V	104	SOIC8 150mil, USON8 2X3mm	UD	UD

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Contact us: ParallelFlash@winbond.com

Serial NAND Flash

Winbond, the worldwide leader in Serial NOR Flash memories, is offering a new family of Serial NAND Flash memory with an SPI interface. These products are an extension of the Serial NOR Flash products at higher densities. To simplify the life of designers looking to store code on their systems at densities beyond the NOR Flash offering of 512Mb density, Winbond is offering Serial NAND products with the same SPI interface with a cost effective NAND based solution at higher densities like 512Mb, 1Gb and 2Gb.

■ Benefits of using Winbond Serial NAND

While NOR flash is more cost effective at lower densities, NAND Flash is a more cost effective memory at densities in the 1Gb and above range.

NAND Flash memory requires a controller to manage the functionality of NAND such as detecting errors in some locations of memory and correcting these errors, managing blocks of memory that have errors in them, and being able to relocate or map the locations with errors to new locations that are error-free.

The Serial NAND family of products are designed to take some of the burden of the controller off its shoulders. These products have built-in ECC (Error Correcting Code that detects and corrects errors) and offer contiguous good memory (bad block management), and hence off loads these functions from the controller.

The added advantage from the Winbond Serial NAND is that it offers continuous read functionality. Typically in most systems, code stored in non-volatile memory, like flash, is transferred to DRAM for faster execution of code with the processor. This is known as code shadowing. System designers are always looking for products that can transfer the code very quickly from flash to DRAM. Winbond Serial NAND offers a continuous read mode that transfers the contents of NAND very quickly to the DRAM. Continuous read mode is also beneficial for XiP (eXecute in Place) operations when larger chunks of data are being transferred.

■ Key Features of the Serial NAND Family

- 46nm SLC NAND technology in Winbond's 12" Fab
- First offering is 1Gb, with 2Gb and 512Kb on roadmap
- Continuous 52MB/s Read Data Throughput ideal for Code-Shadowing applications
- Fully backward-compatible SpiFlash Instruction Set with minor additions
- Low pin-count SpiFlash packages (WSO8, TFBGA-24) with MCP options
- On Chip 1-Bit ECC correction and Bad Block Management
- Flexible device configurations by customers' need (Buffer/Continuous Read, Array/Device Lock-Down/OTP/write protection)
- Industrial grades

■ 2Gb (256MB)

Part No.	Voltage	I/O	Page Size	Speed (MHz)	Package	Status ^{1,2}	Automotive
W25M02GV	2.7V - 3.6V	x1/x4	2KB+64B	104	WS0N8 8X6mm VFBGA24 8X6mm	P	P
W25M02GW	1.7V - 1.95V	x1/x4	2KB+64B	104	WS0N8 8X6mm ³ VFBGA24 8X6mm ³	P	S

■ 1Gb (128MB)

Part No.	Voltage	I/O	Page Size	Speed (MHz)	Package	Status ^{1,2}	Automotive
W25N01GV	2.7V - 3.6V	x1/x4	2KB+64B	104	SOP16 WS0N8 8X6mm VFBGA24 8X6mm	P	P
W25N01GW	1.7V - 1.95V	x1/x4	2KB+64B	104	SOP16 WS0N8 8X6mm VFBGA24 8X6mm	P	P

■ 512Mb (64MB)

Part No.	Voltage	I/O	Page Size	Speed (MHz)	Package	Status ^{1,2}	Automotive
W25N512GV	2.7V - 3.6V	x1/x4	2KB+64B	104	WS0N8 8X6mm WS0N8 6X5mm VFBGA24 8X6mm	P	UD
W25N512GW	1.7V - 1.95V	x1/x4	2KB+64B	104	WS0N8 8X6mm WS0N8 6X5mm VFBGA24 8X6mm	P	UD

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Contact us: ParallelFlash@winbond.com



winbond

We Deliver

SLC NAND Flash

■ Industry Standard Compatible SLC NAND Flash Family

These SLC NAND Flash products are a direct drop-in replacement to the SLC NAND products available in the industry from different suppliers at this time and the products are fully compatible. The command set, the interface and the packages are the same and the feature set that Winbond offers is a superset of the features that other suppliers offer.

■ Competitive Advantage:

The Winbond SLC NAND products offer a page size of 2048+64 Bytes which is large enough to accommodate 4-bit or 8-bit ECC operation and hence can offer a more robust NAND solution compared to the competition. These NAND devices provide higher performance because of cache read/program operation. Most of these products offer 1-bit ECC and hence can support several platforms that need products with 1-bit ECC built-in. These products will be supported for a long period of time and customers can expect to receive long term support of these products for several more years.

■ Applications:

NAND Flash memory products from Winbond are used in multiple applications including the Internet of Things, Automotive, Networking, Storage, Set-Top-Box, DSL and Cable modems, Digital TV, Mobile phones, Printers, Industrial as well as other applications.



■ 8Gb (1GB)

Part No.	Voltage	I/O	Page Size	Speed (ns)	Package	Status ^{1,2}	Automotive
W29N08GV	2.7V - 3.6V	x8	2KB+64B	25	TSOP48 VFBGA63 9x11mm	P	P

■ 4Gb (512MB)

Part No.	Voltage	I/O	Page Size	Speed (ns)	Package	Status ^{1,2}	Automotive
W29N04GV	2.7V - 3.6V	x8	2KB+64B	25	TSOP48 VFBGA63 9x11mm	P	P
W29N04GZ	1.7V - 1.95V	x8	2KB+64B	35	VFBGA63 9x11mm	P	UD
W29N04GW	1.7V - 1.95V	x16	2KB+64B	35	VFBGA63 9x11mm	P	UD

■ 2Gb (256MB)

Part No.	Voltage	I/O	Page Size	Speed (ns)	Package	Status ^{1,2}	Automotive
W29N02GV	2.7V - 3.6V	x8	2KB+64B	25	TSOP48 VFBGA63 9x11mm	P	P
W29N02KV	2.7V - 3.6V	x8	2KB+128B	25	TSOP48 VFBGA48 8X6.5mm VFBGA63 9X11mm	S	UD
W29N02GZ	1.7V - 1.95V	x8	2KB+64B	35	TSOP48 VFBGA63 9X11mm	P	S
W29N02GW	1.7V - 1.95V	x16	2KB+64B	35	TSOP48 VFBGA63 9X11mm	P	S

■ 1Gb (128MB)

Part No.	Voltage	I/O	Page Size	Speed (ns)	Package	Status ^{1,2}	Automotive
W29N01HV	2.7V - 3.6V	x8	2KB+64B	25	TSOP48 VFBGA48 8X6.5mm	P	P
W29N01HZ	1.7V - 1.95V	x8	2KB+64B	35	TSOP48 VFBGA48 8X6.5mm VFBGA63 9X11mm	P	S
W29N01HW	1.7V - 1.95V	x16	2KB+64B	35	TSOP48 VFBGA48 8X6.5mm VFBGA63 9X11mm	P	S

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Contact us: NANDFlash@winbond.com

NAND Based MCP

Multi-Chip Package (MCP) memory product family consists of a 1.8V NAND Flash Memory device combined with a 1.8V Low Power SDRAM device in one package to provide the most space effective solution for saving area on the PCB. This benefit becomes more critical in small PCBs for applications like modules and designs with a small PCB area, particularly for mobile and portable applications.

■ Self-owned DRAM and SLC NAND Flash Technology

Winbond Electronics Corp. is a Memory IC Company engaged in DRAM and Flash design, manufacturing and sales services. From product design, research and development, wafer fabrication to marketing of brand name products, Winbond endeavors to provide its global clientele top quality of low to medium density memory solutions.

■ Self-owned 12-inch fab

Winbond specializes in the design of high-performance, low-power memory, and riding on the strength of having a 12-inch fab, offers a whole series of SLC code storage NAND flash memory and Mobile DRAM products. Our in house wafer fabrication provides customers with full commitment in capacity support as well as delivery flexibility.

■ NAND + LPDDR

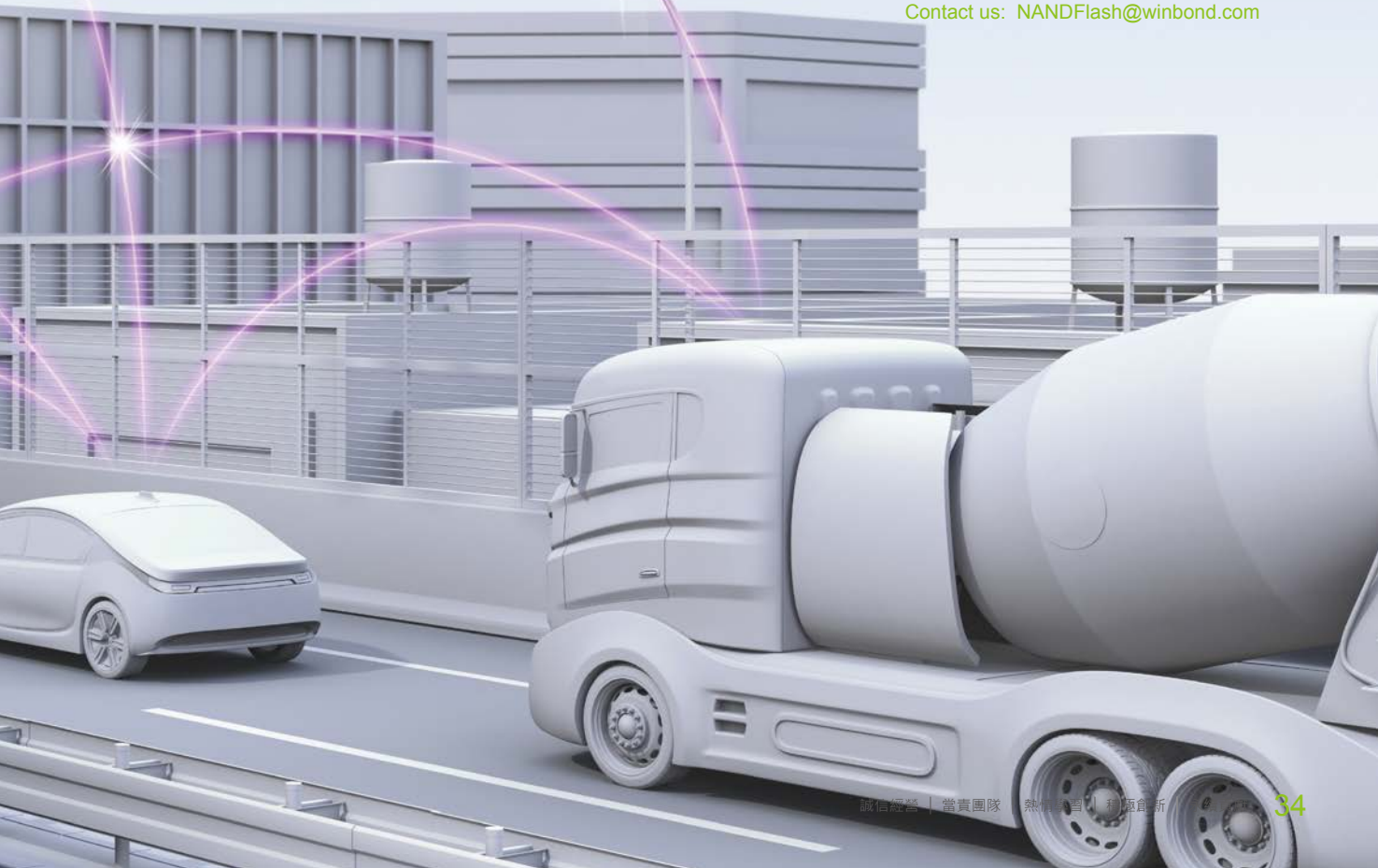
Ball	Package Size (mm)	Part No.	Density		I/O Bus		DRAM Type	Status
			Flash	DRAM	Flash	DRAM		
130	8x9x1.0	W71NW10GC1DW	1Gb	512Mb	8	16	LPDDR1	N
		W71NW11HC1DW	1Gb	512Mb	16	16	LPDDR1	N
		W71NW20GD3DW	2Gb	1Gb	8	32	LPDDR1	N
		W71NW21GD1DW	2Gb	1Gb	16	16	LPDDR1	N

■ NAND + LPDDR2

Ball	Package Size (mm)	Part No.	Density		I/O Bus		DRAM Type	Status
			Flash	DRAM	Flash	DRAM		
121	8x8x0.8	W71NW11GE1EW	1Gb	512Mb	16	16	LPDDR2	P
		W71NW11GF1EW	1Gb	1Gb	16	16	LPDDR2	P
162	8x10.5x1.0	W71NW10HE3FW	1Gb	512Mb	8	32	LPDDR2	P
		W71NW10GF3FW	1Gb	1Gb	8	32	LPDDR2	P
		W71NW20GF3FW	2Gb	1Gb	8	32	LPDDR2	P

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Contact us: NANDFlash@winbond.com



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We Deliver

SpiStack Flash (NOR+NAND)

Winbond is the first company to offer the new SpiStack® W25M Memory Series for “stacking” of homogeneous or heterogeneous flash, thus achieving memories of varying densities for code and data storage, while providing designers with flash solutions most appropriate for their design requirements. SpiStack architecture offers designers maximum flexibility in tailoring flash solutions to meet their specific memory-density and application requirements. The W25M Series provides a wide range of densities in the well-established 8-pin package to which designers are accustomed. W25M memories also feature the popular, multi-IO SpiFlash® interface featuring the popular Serial Peripheral Interface (SPI) and command set.

SpiStack homogeneous memories are formed by stacking SpiFlash dies – for example, two 256Mb dies combining to form a single SpiFlash 512Mb NOR memory in the industry-standard 8-pin 8x6mm WSON package. This stacked product, W25M512JV, is also available now in 16-pin SOIC or 24-pad BGA packages. SpiStack heterogeneous memories are formed by stacking a NOR die with a NAND die, such as a 64Mb SpiFlash NOR blended with a 1Gb Serial NAND die, which gives designers the flexibility to store code in the NOR die and data in the NAND memory.

Individual components forming the stacked solution have clock rates up to 104MHz achieving an equivalent of 416MHz (50M-Byte/S transfer rate) when using Quad-SPI. Multiple SpiFlash dies, each with density ranging from 16Mb to 2Gb, can be stacked with any combination of NOR and NAND dies. A NOR die can be used to store the boot code, which offer better endurance and retention, and fast random access time. A NAND memory can be used to store data and to back up the boot code. A NAND die can also be used to upload the working memory data quickly whenever the system power goes down, since its programming time is much faster than NOR. It improves the system quality by storing up-to-date code residing in the working memory for later usage.

SpiStack supports concurrent operation so that code execution is not interrupted for data updates. All SpiStack features are supported so that backward compatibility is conserved with the addition of a simple software die select instruction (C2h) and a factory-assigned die ID number.

W25M SpiStack Family

- Stack flash dies to form a higher density part of choice
- User can select based on specific density requirement
- Serial Peripheral Interface (SPI)
- Backward compatible to existing SpiFlash

Homogeneous stacking – Two or more dies

- NOR dies combined using 1Mb to 256M-bit dies
- NAND dies combined using 512Mb to 2Gb dies

Heterogeneous stacking – Two or more dies

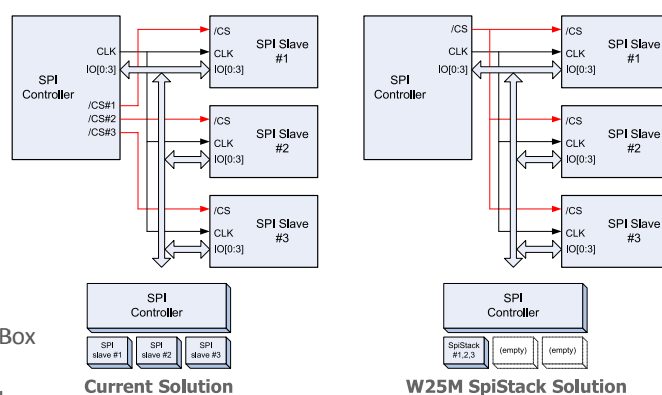
- NOR and NAND dies stacked together
- Concurrent Operation

- Read operation on one die + Write / Erase operation on another die
- Code execution not interrupted for data updates

Wide Range of Applications

- Mobile phones, Cameras, Printer, Servers, Set Top Box
- Automotive, Bluetooth, GPS, Digital-TV, DSP, FPGA
- WLAN, DSL/Cable Modem, Gateway, Industrial and more

W25M *spistack* Memory



■ 128Mb(16MB) Serial NOR + 1Gb(128MB) Serial NAND

Part No.	Voltage	I/O	Page Size	Speed (MHz)	Package	Status ^{1,2}	Automotive
W25M121AV	2.7V - 3.6V	x4/x4	2KB+64B	104	WSO8 8X6mm	P	P
W25M121AW	1.7V - 1.95V	x4/x4	2KB+64B	104	WSO8 8X6mm	UD	UD

■ 64Mb(8MB) Serial NOR + 1Gb(128MB) Serial NAND

Part No.	Voltage	I/O	Page Size	Speed (MHz)	Package	Status ^{1,2}	Automotive
W25M641AV	2.7V - 3.6V	x4/x4	2KB+64B	104	WSO8 8X6mm	P	P
W25M641AW	1.7V - 1.95V	x4/x4	2KB+64B	104	WSO8 8X6mm	UD	UD

■ 32Mb(4MB) Serial NOR + 1Gb(128MB) Serial NAND

Part No.	Voltage	I/O	Page Size	Speed (MHz)	Package	Status ^{1,2}	Automotive
W25M321AV	2.7V - 3.6V	x4/x4	2KB+64B	104	WSO8 8X6mm	P	P
W25M321AW	1.7V - 1.95V	x4/x4	2KB+64B	104	WSO8 8X6mm	UD	UD

■ 16Mb(2MB) Serial NOR + 1Gb(128MB) Serial NAND

Part No.	Voltage	I/O	Page Size	Speed (MHz)	Package	Status ^{1,2}	Automotive
W25M161AV	2.7V - 3.6V	x4/x4	2KB+64B	104	WSO8 8X6mm	P	P
W25M161AW	1.7V - 1.95V	x4/x4	2KB+64B	104	WSO8 8X6mm	P	P

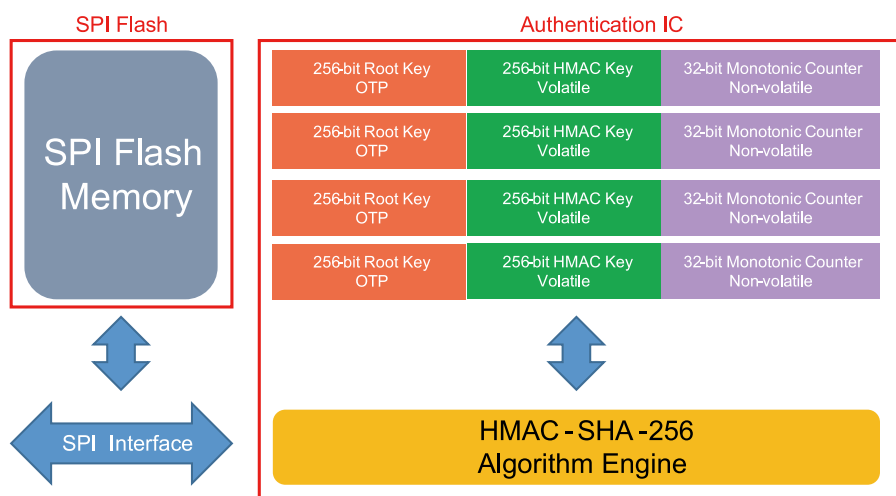
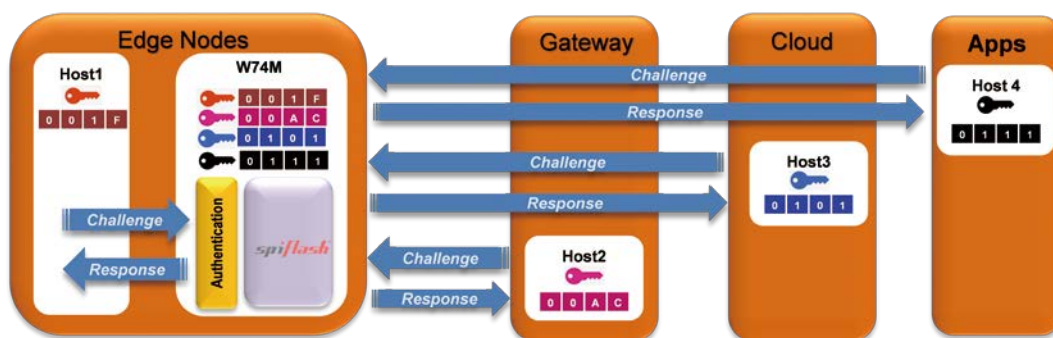
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Contact us: NANDFlash@winbond.com

Authentication Flash

Winbond W74M product family comes with standard HMAC-SHA-256 crypto accelerator and 4 separate Monotonic Flash Counters that are HMAC-signed by individual secret keys. A system utilizing each Monotonic Flash Counter can not only verify the integrity and authenticity of the counter values, but also adds a timestamp to the message/information transmitted with resistance to replay attacks. W74M enables system designers to strengthen code/data storage as well as delivers increased security for emerging IoT devices demanding multi-layered authentication.



■ 1Gb (128MB)

Part No.	Features	Voltage	Speed (MHz)	Package	Status ^{1,2}	Automotive
W74M01GV	2048+64Byte page size 128K+4KByte block size Dual/Quad-SPI, HW authentication x 4	2.7V - 3.6V	80	WS0N8 8X6mm	P	P

■ 256Mb (32MB)

Part No.	Features	Voltage	Speed (MHz)	Package	Status ^{1,2}	Automotive
W74M25JV	131072pages, 4KB sectors, 32/64KB blocks, Dual/Quad-SPI, QPI, Enhanced ³ , HW authentication x 4	2.7V - 3.6V	80	WS0N8 8X6mm	P	UD
W74M25JW	131072pages, 4KB sectors, 32/64KB blocks, Dual/Quad-SPI, QPI, Enhanced ³ , HW authentication x 4	1.65V - 1.95V	80	WS0N8 8X6mm	S	UD

■ 128Mb (16MB)

Part No.	Features	Voltage	Speed (MHz)	Package	Status ^{1,2}	Automotive
W74M12JV	65536 pages, 4KB sectors, 32/64KB blocks, Dual/Quad-SPI, QPI, Enhanced ^{^3} , HW authentication x 4	2.7V - 3.6V	80	WSO8 6X5mm, SOP8 208mil	P	UD
W74M12JW	65536 pages, 4KB sectors, 32/64KB blocks, Dual/Quad-SPI, QPI, Enhanced ^{^3} , HW authentication x 4	1.65V - 1.95V	80	WSO8 6X5mm, SOP8 208mil	UD	UD

■ 64Mb (8MB)

Part No.	Features	Voltage	Speed (MHz)	Package	Status ^{1,2}	Automotive
W74M64JV	32768 pages, 4KB sectors, 32/64KB blocks, Dual/Quad-SPI, QPI, Enhanced ^{^3} , HW authentication x 4	2.7V - 3.6V	80	SOP8 208 mil	P	UD
W74M64JW	32768 pages, 4KB sectors, 32/64KB blocks, Dual/Quad-SPI, QPI, Enhanced ^{^3} , HW authentication x 4	1.65V - 1.95V	80	SOP8 208 mil	UD	UD

■ 32Mb (4MB)

Part No.	Features	Voltage	Speed (MHz)	Package	Status ^{1,2}	Automotive
W74M32FV	16384 pages, 4KB sectors, 32/64KB blocks, Dual/Quad-SPI, QPI, Enhanced ^{^3} , HW authentication x 4	2.7V - 3.6V	80	SOP8 208 mil	P	UD
W74M32JW	16384 pages, 4KB sectors, 32/64KB blocks, Dual/Quad-SPI, QPI, Enhanced ^{^3} , HW authentication x 4	1.65V - 1.95V	80	SOP8 208 mil	UD	UD

■ 0Mb

Part No.	Features	Voltage	Speed (MHz)	Package	Status ^{1,2}	Automotive
W74M00AV	HW authentication x 4	2.7V - 3.6V	80	SOP8 208 mil, SOP8 150 mil	P	P
W74M00AW	HW authentication x 4	1.65V - 1.95V	80	SOP8 208 mil, SOP8 150 mil	P	UD

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Contact us: NANDFlash@winbond.com

KGD

We offer various types of Parallel Flash and Serial Flash KGD products.

Contact us: Flash-KGD@winbond.com.

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We Deliver

NOTE

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WORLDWIDE SALES OFFICE

Winbond Electronics Corp. (Headquarters, CTSP Site)

No. 8, Keya 1st Rd., Daya Dist., Central Taiwan Science Park,
Taichung City, 42881, Taiwan
Tel: 886-4-2521-8168

Jhubei Office

6F., No.38, Gaotie 1st Rd., Jhubei City, Hsinchu County 30273, Taiwan
Tel: 886-3-567-8168

Taipei Office

2F, No.192, Jingye 1st Rd., Zhongshan Dist.,
Taipei City 10462, Taiwan
Tel: 886-2-8177-7168

Winbond Electronics Corporation America

2727 North First St., San Jose,
CA 95134, U.S.A.
Tel: 1-408-943-6666

Winbond Electronics (Suzhou) Limited

Room 1206, Kingboard Plaza(Building B, 12 floor), No.505, Guangming Road,
Huaqiao Town, Kunshan City, Jiangsu Province, China
Tel : 86-512-8163-8168

Winbond Electronics(Suzhou) Limited -Shenzhen office

8F Microprofit Building, Gaoxinnan 6 Road, High-Tech Industrial Park,
Nanshan Dist. Shenzhen, P.R. China
Tel : 86-755-3301-9858

Winbond Electronics (H.K.) Limited

Unit 9-11, 22F, Millennium City 2,
378 Kwun Tong Rd., Kowloon, Hong Kong
Tel: 852-2751-3126

Winbond Electronics Corporation Japan

Shin-Yokohama Square Bldg. 9F 2-3-12 Shin-Yokohama,Kouhoku-ku,
Yokohama, kanagawa 222-0033, Japan
Tel: 81-45-478-1881

